

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC042N03MS G	**Issued**	07. April 2021
MA#	MA001705952		
Package	PG-TDSON-8-40	**Weight***	112.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.426	1.27	1.27	12725	12725
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		130	
	non noble metal	iron	7439-89-6	0.049	0.04		435	
	non noble metal	copper	7440-50-8	48.649	43.41	43.46	434048	434613
wire	non noble metal	copper	7440-50-8	0.047	0.04	0.04	422	422
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		744	
	plastics	epoxy resin	-	6.588	5.88		58778	
	inorganic material	silicondioxide	60676-86-0	35.025	31.25	37.20	312489	372011
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13562	13562
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1414	1414
solder	non noble metal	tin	7440-31-5	0.032	0.03		284	
	noble metal	silver	7440-22-4	0.040	0.04		355	
	non noble metal	lead	7439-92-1	1.518	1.35	1.42	13547	14186
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.09	15.11	150871	151067
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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